

THS6182

SLLS544E – SEPTEMBER 2002 – REVISED JULY 2003

LOW POWER DISSIPATION ADSL LINE DRIVER

FEATURES

- Low Power Dissipation Increases ADSL Line Card Density
- Low THD of -88 dBc ($100\text{-}\Omega$, 1 MHz)
- Low MTPR Driving $+20$ dBm on the Line
 - -76 dBc With High Bias Setting
 - -74 dBc With Low Bias Setting
- Wide Output Swing of $44V_{pp}$ Differential Into a $200\text{-}\Omega$ Differential Load ($V_{CC} = \pm 12$ V)
- High Output Current of 600 mA (Typ)
- Wide Supply Voltage Range of ± 5 V to ± 15 V
- Pin Compatible With EL1503C and EL1508C
 - Multiple Package Options
- Multiple Power Control Modes
 - 11 mA/ch Full Bias Mode
 - 7.5 mA/ch Mid Bias Mode
 - 4 mA/ch Low Bias Mode
 - 0.25 mA/ch Shutdown Mode
 - I_{ADJ} Pin for User Controlled Bias Current
 - Stable Operation Down to 2 mA/ch
- Low Noise for Increased Receiver Sensitivity
 - 3.2 nV/ $\sqrt{\text{Hz}}$ Voltage Noise
 - 1.5 pA/ $\sqrt{\text{Hz}}$ Noninverting Current Noise
 - 10 pA/ $\sqrt{\text{Hz}}$ Inverting Current Noise

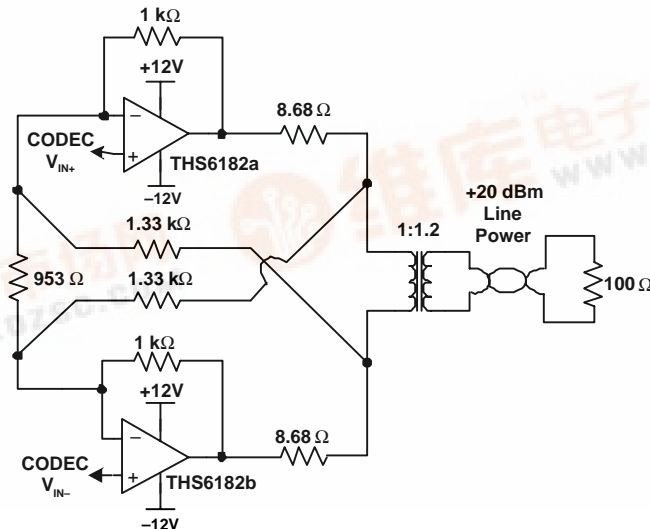
APPLICATIONS

- Ideal for Full Rate ADSL Applications

DESCRIPTION

The THS6182 is a current feedback differential line driver ideal for full rate ADSL systems. Its extremely low power dissipation is ideal for ADSL systems that must achieve high densities in ADSL central office rack applications. The unique architecture of the THS6182 allows the quiescent current to be much lower than existing line drivers while still achieving very high linearity without the need for excess open loop gain. Fixed multiple bias settings of the amplifiers allow for enhanced power savings for line lengths where the full performance of the amplifier is not required. To allow for even more flexibility and power savings, an I_{ADJ} pin is available to further lower the bias currents while maintaining stable operation with as little as 2 mA per channel. The wide output swing of $44 V_{pp}$ differentially with ± 12 V power supplies allows for more dynamic headroom, keeping distortion at a minimum. With a low 3.2 nV/ $\sqrt{\text{Hz}}$ voltage noise coupled with a low 10 pA/ $\sqrt{\text{Hz}}$ inverting current noise, the THS6182 increases the sensitivity of the receive signals, allowing for better margins and reach.

Typical ADSL CO Line Driver Circuit Utilizing Active Impedance





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage.

ORDERING INFORMATION

PRODUCT	PACKAGE	PACKAGE CODE	SYMBOL	T _A	ORDER NUMBER	TRANSPORT MEDIA
THS6182RHF	Leadless 24-pin 4 mm x 5 mm PowerPAD™	RHF–24	6182	–40°C to 85°C	THS6182RHFR	Tape and reel (3000 devices)
					THS6182RHFT	Tape and reel (250 devices)
THS6182D	SOIC–16	D–16	THS6182		THS6182D	Tube (40 devices)
					THS6182DR	Tape and reel (2500 devices)
THS6182DW	SOIC–20	DW–20	THS6182		THS6182DW	Tube (25 devices)
					THS6182DWR	Tape and reel (2000 devices)

PACKAGE DISSIPATION RATINGS⁽¹⁾

PACKAGE	PowerPAD SOLDERED ⁽²⁾ θ _{JA}	PowerPAD NOT SOLDERED ⁽³⁾ θ _{JA}	θ _{JC}
RHF-24	32°C/W	74°C/W	1.7°C/W
D-16	–	62.9°C/W	25.7°C/W
DW-20	–	45.4°C/W	16.4°C/W

(1) θ_{JA} values shown are typical for standard test PCBs only.

(2) For high power dissipation applications, use of the PowerPAD package and soldering the PowerPAD to the PCB is required. Failure to do so may result in reduced reliability and/or lifetime of the device. See TI technical brief SLMA002 for more information about utilizing the PowerPAD thermally enhanced package.

(3) Use of packages without the PowerPAD or not soldering the PowerPAD to the PCB, should be limited to low-power dissipation applications.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range unless otherwise noted⁽¹⁾

ELECTRICAL	THS6182
Supply voltage, V _{CC} ⁽²⁾	±16.5 V
Input voltage, V _I	±V _{CC}
Output current, I _O ⁽²⁾	1000 mA
Differential input voltage, V _{IO}	±2 V
THERMAL	
Maximum junction temperature, any condition ⁽³⁾ , T _J	150°C
Maximum junction temperature, continuous operation, long term reliability ⁽⁴⁾ , T _J	125°C
Operating free–air temperature, T _A	–40°C to 85°C
Storage temperature, T _{sgt}	–65°C to 150°C
Lead temperature, 1,6 mm (1/16–inch) from case for 10 seconds	300°C

(1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The THS6182 may incorporate a PowerPAD on the underside of the chip. This acts as a heatsink and must be connected to a thermally dissipating plane for proper power dissipation. Failure to do so may result in exceeding the maximum junction temperature that could permanently damage the device. See TI Technical Brief SLMA002 for more information about utilizing the PowerPAD thermally enhanced package.

(3) The absolute maximum temperature under any condition is limited by the constraints of the silicon process.

(4) The maximum junction temperature for continuous operation is limited by package constraints. Operation above this temperature may result in reduced reliability and/or lifetime of the device.

ABSOLUTE MAXIMUM RATINGS

ESD		
ESD ratings	HBM	500 V
	CDM	1500 V
	MM	200 V

RECOMMENDED OPERATING CONDITIONS

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC+} to V_{CC-}	Dual supply	± 5	± 12	± 15	V
	Single supply	10	24	30	
Operating free-air temperature, T_A		-40		85	$^{\circ}\text{C}$
Operating junction temperature, continuous operation T_J		-40		125	$^{\circ}\text{C}$
Normal storage temperature, T_{Stg}		-40		85	$^{\circ}\text{C}$

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range, $T_A = 25^{\circ}\text{C}$, $V_{CC} = \pm 12\text{ V}$, $R_F = 2\text{ k}\Omega$, Gain = +5, $I_{ADJ} = \text{Bias1} = \text{Bias2} = 0\text{ V}$, $R_L = 50\text{ }\Omega$ (unless otherwise noted)

NOISE/DISTORTION PERFORMANCE								
PARAMETER			TEST CONDITIONS		MIN	TYP	MAX	UNIT
MTPR	Multitone power ratio		Gain =+9.5, 163 kHz to 1.1 MHz DMT, +20 dBm Line Power, See Figure 1 for circuit			-76		dBc
	Receive band spillover		Gain =+5, 25 kHz to 138 kHz with MTPR signal applied, See Figure 1 for circuit			-95		dBc
HD	Harmonic distortion, V _{O(PP)} = 2 V f = 1 MHz		2 nd harmonic	Differential load = 200 Ω		-88		dBc
				Differential load = 50 Ω		-70		
			3 rd harmonic	Differential load = 200 Ω		-107		dBc
				Differential load = 50 Ω		-84		
V _n	Input voltage noise		V _{CC} = ±5 V, ±12 V, ±15 V, f = 100 kHz			3.2		nV/√Hz
I _n	Input current noise	+Input	V _{CC} = ±5 V, ±12 V, ±15 V, f = 100 kHz			1.5		pA/√Hz
		-Input				10		
Crosstalk			f = 1 MHz, V _{O(PP)} = 2 V, V _{CC} = ±5 V, ±12 V, ±15 V	R _L = 100 Ω		-65		dBc
				R _L = 25 Ω		-60		dBc
OUTPUT CHARACTERISTICS								
V _O	Single-ended output voltage swing		V _{CC} = ±5 V	R _L = 100 Ω		±3.9	±4.1	V
				R _L = 25 Ω		±3.7	±3.9	
			V _{CC} = ±12 V	R _L = 100 Ω		±10.7	±11.0	V
				R _L = 25 Ω		±10.0	±10.6	
			V _{CC} = ±15 V	R _L = 100 Ω		±13.5	±13.9	V
				R _L = 25 Ω		±12.7	±13.4	
I _O	Output current ⁽¹⁾		R _L = 5 Ω	V _{CC} = ±5 V		±350	±400	mA
			R _L = 10 Ω	V _{CC} = ±12 V		±450	±600	
				V _{CC} = ±15 V		±450	±600	
I _(SC)	Short-circuit current ⁽¹⁾		R _L = 1 Ω	V _{CC} = ±12 V		1000		mA
	Output resistance		Open-loop			6		Ω
	Output resistance—terminate mode		f = 1 MHz,	Gain = +10		0.05		Ω
	Output resistance—shutdown mode		f = 1 MHz,	Open-loop		8.5		kΩ

⁽¹⁾ A heatsink is required to keep the junction temperature below absolute maximum rating when an output is heavily loaded or shorted. See Absolute Maximum Ratings section for more information.

ELECTRICAL CHARACTERISTICS (continued)

over recommended operating free-air temperature range, $T_A = 25^\circ\text{C}$, $V_{CC} = \pm 12\text{ V}$, $R_F = 2\text{ k}\Omega$, Gain = +5, $I_{ADJ} = \text{Bias1} = \text{Bias2} = 0\text{ V}$, $R_L = 50\ \Omega$ (unless otherwise noted)

POWER SUPPLY						
PARAMETER		TEST CONDITIONS		MIN	TYP	MAX
V_{CC}	Operating range	Dual supply		± 4	± 12	± 16.5
		Single supply		8	24	33
I_{CC}	Quiescent current (each driver) ⁽¹⁾ Full-bias mode (Bias-1 = 0, Bias-2 = 0) (Trimmed with $V_{CC} = \pm 15\text{ V}$ at 25°C)	$V_{CC} = \pm 5\text{ V}$	$T_A = 25^\circ\text{C}$		9.7	10.7
			$T_A = \text{full range}$			11.7
		$V_{CC} = \pm 12\text{ V}$	$T_A = 25^\circ\text{C}$		11	12
			$T_A = \text{full range}$			12.5
		$V_{CC} = \pm 15\text{ V}$	$T_A = 25^\circ\text{C}$		11.5	12.5
			$T_A = \text{full range}$			13
	Quiescent current (each driver) Variable bias modes, $V_{CC} = \pm 12\text{ V}$	Mid; Bias-1 = 1, Bias-2 = 0			7.5	8.5
		Low; Bias-1 = 0, Bias-2 = 1			4	5
		Shutdown; Bias-1 = 1, Bias-2 = 1			0.25	0.9
PSRR	Power supply rejection ratio ($\Delta V_{CC} = \pm 1\text{ V}$)	$V_{CC} = \pm 5\text{ V}$, $\Delta V_{CC} = \pm 0.5\text{ V}$	$T_A = 25^\circ\text{C}$	-50	-56	
			$T_A = \text{full range}$	-47		
		$V_{CC} = \pm 12\text{ V}, \pm 15\text{ V}$, $\Delta V_{CC} = \pm 1\text{ V}$	$T_A = 25^\circ\text{C}$	-56	-60	
			$T_A = \text{full range}$	-53		

(1) Approximately 0.5 mA (total) flows from V_{CC+} to GND for internal logic control bias.

DYNAMIC PERFORMANCE						
PARAMETER		TEST CONDITIONS		MIN	TYP	MAX
BW	Single-ended small-signal bandwidth (-3 dB), $V_O = 0.1\text{ V}_{rms}$	$R_L = 100\ \Omega$	Gain = +1, $R_F = 1.2\text{ k}\Omega$		100	
			Gain = +2, $R_F = 1\text{ k}\Omega$		80	
			Gain = +5, $R_F = 1\text{ k}\Omega$		35	
			Gain = +10, $R_F = 1\text{ k}\Omega$		20	
		$R_L = 25\ \Omega$	Gain = +1, $R_F = 1.5\text{ k}\Omega$		65	
			Gain = +2, $R_F = 1\text{ k}\Omega$		60	
			Gain = +5, $R_F = 1\text{ k}\Omega$		40	
			Gain = +10, $R_F = 1\text{ k}\Omega$		22	
SR	Single-ended slew-rate ⁽²⁾	$V_O = 10\text{ V}_{pp}$	Gain = +5		450	

(2) Slew-rate is defined from the 25% to the 75% output levels

DC PERFORMANCE							
PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V _{OS}	Input offset voltage	V _{CC} = ± 5 V, ±12 V, ±15 V	T _A = 25°C		1	20	mV
			T _A = full range		25		
	Differential offset voltage		T _A = 25°C	0.5	10		
			T _A = full range		15		
	Offset drift			T _A = full range		50	μV/°C
I _{IB}	–Input bias current	V _{CC} = ± 5 V, ±12 V, ±15 V	T _A = 25°C		8	15	μA
			T _A = full range		20		
	+ Input bias current		T _A = 25°C	8	15		
			T _A = full range		20		
Z _{OL}	Open loop transimpedance	R _L = 1 kΩ, V _{CC} = ± 12 V, ±15 V,			900		kΩ

ELECTRICAL CHARACTERISTICS (CONTINUED)

over recommended operating free-air temperature range, $T_A = 25^\circ\text{C}$, $V_{CC} = \pm 12\text{ V}$, $R_F = 2\text{ k}\Omega$, Gain = +5, $I_{ADJ} = \text{Bias1} = \text{Bias2} = 0\text{ V}$, $R_L = 50\text{ }\Omega$ (unless otherwise noted)

INPUT CHARACTERISTICS						
PARAMETER		TEST CONDITIONS		MIN	TYP	MAX
V_{ICR}	Input common-mode voltage range	$V_{CC} = \pm 5\text{ V}$	$T_A = 25^\circ\text{C}$	± 2.7	± 3.0	V
			$T_A = \text{full range}$	± 2.6		
		$V_{CC} = \pm 12\text{ V}$	$T_A = 25^\circ\text{C}$	± 9.5	± 9.8	V
			$T_A = \text{full range}$	± 9.3		
		$V_{CC} = \pm 15\text{ V}$	$T_A = 25^\circ\text{C}$	± 12.4	± 12.7	V
			$T_A = \text{full range}$	± 12.1		
CMRR	Common-mode rejection ratio	$V_{CC} = \pm 5\text{ V}, \pm 12\text{ V}, \pm 15\text{ V}$	$T_A = 25^\circ\text{C}$	48	54	dB
			$T_A = \text{full range}$	44		
R_I	Input resistance	+ Input			800	$\text{k}\Omega$
		– Input			30	Ω
C_I	Input capacitance				1.7	pF

LOGIC CONTROL CHARACTERISTICS						
PARAMETER		TEST CONDITIONS		MIN	TYP	MAX
V_{IH}	Bias pin voltage for logic 1	Relative to GND pin voltage		2.0		V
V_{IL}	Bias pin voltage for logic 0	Relative to GND pin voltage				0.8
I_{IH}	Bias pin current for logic 1	$V_{IH} = 3.3\text{ V}, \text{ GND} = 0\text{ V}$			4	30
I_{IL}	Bias pin current for logic 0	$V_{IL} = 0.5\text{ V}, \text{ GND} = 0\text{ V}$			1	10
Transition time—logic 0 to logic 1 ⁽¹⁾					1	μs
Transition time—logic 1 to logic 0 ⁽¹⁾					1	μs

(1) Transition time is defined as the time from when the logic signal is applied to the time when the supply current has reached half its final value.

LOGIC TABLE			
BIAS-1	BIAS-2	FUNCTION	DESCRIPTION
0	0	Full bias mode	Amplifiers ON with lowest distortion possible (default state)
1	0	Mid bias mode	Amplifiers ON with power savings with a reduction in distortion performance
0	1	Low bias mode	Amplifiers ON with enhanced power savings and a reduction of distortion performance
1	1	Shutdown mode	Amplifiers OFF and output has high impedance

NOTE: The default state for all logic pins is a logic zero (0).

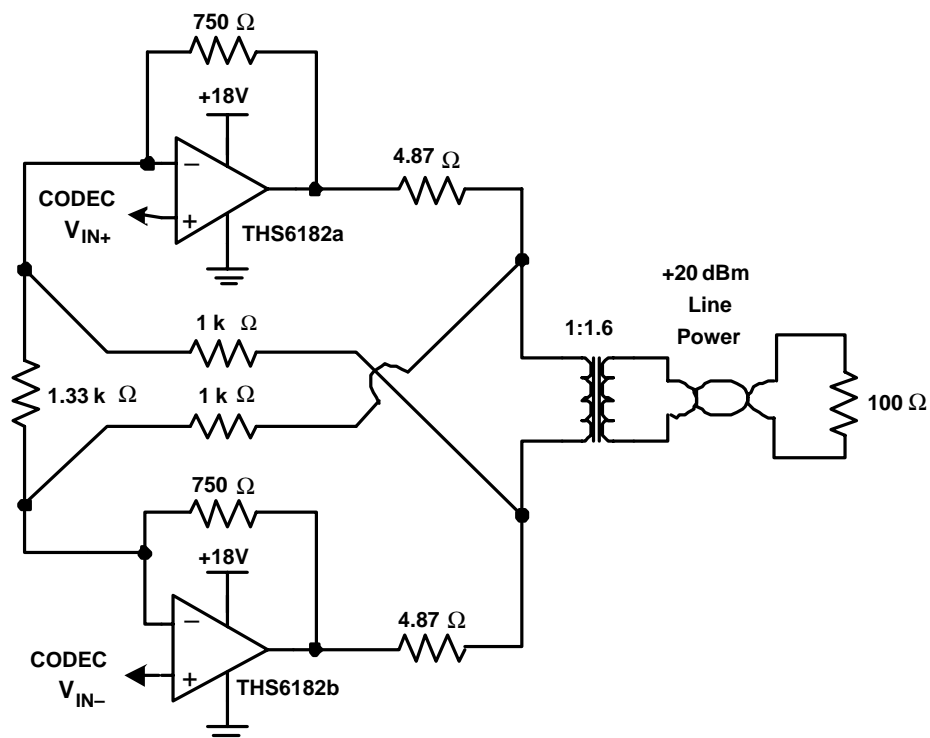
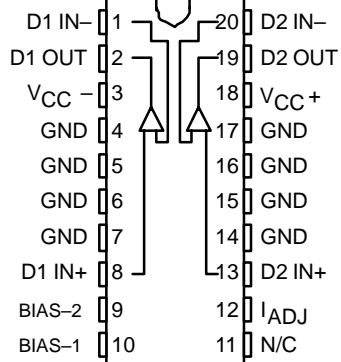


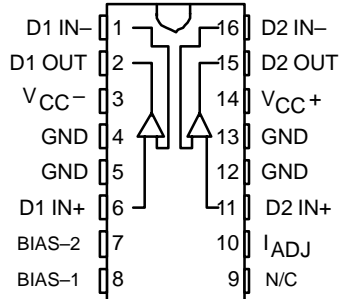
Figure 1. Single-Supply ADSL CO Line Driver Circuit Utilizing Active Impedance (SF = 4)

PIN ASSIGNMENTS

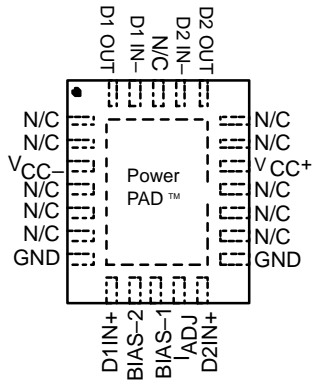
**THS6182
SOIC-20 (DW) PACKAGE
(TOP VIEW)**



**THS6182
SOIC-16 (D) PACKAGE
(TOP VIEW)**



**THS6182
Leadless 24-pin PowerPAD™
4 mm X 5 mm (RHF) PACKAGE
(TOP VIEW)**



TYPICAL CHARACTERISTICS

Table of Graphs

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2nd Harmonic distribution	vs Output voltage	61 – 64
3rd Harmonic distribution	vs Output voltage	65 – 68

TYPICAL CHARACTERISTICS

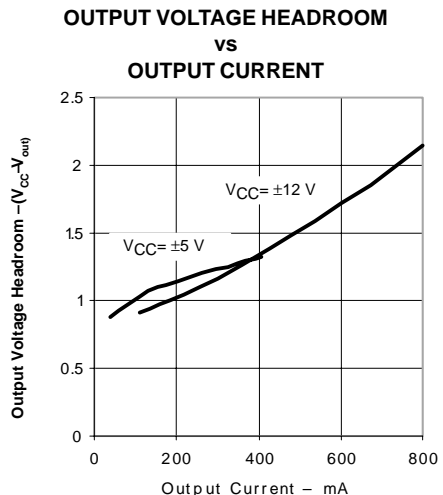


Figure 2

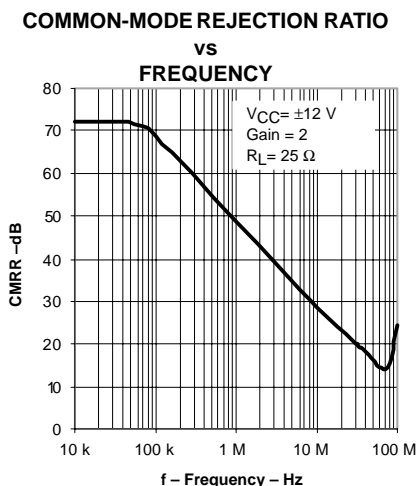


Figure 3

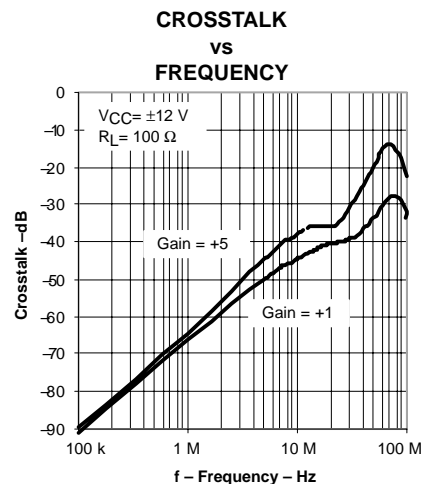


Figure 4

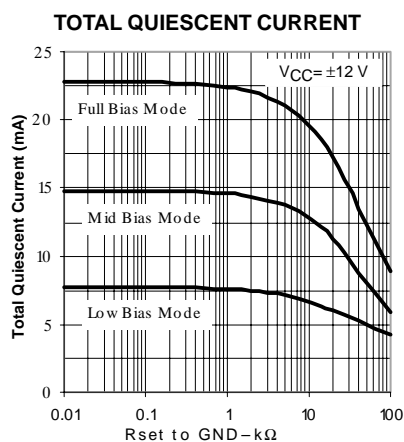


Figure 5

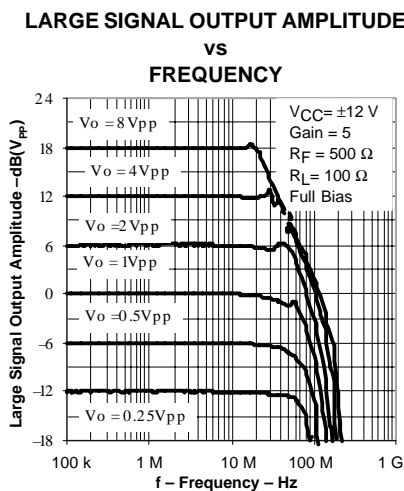


Figure 6

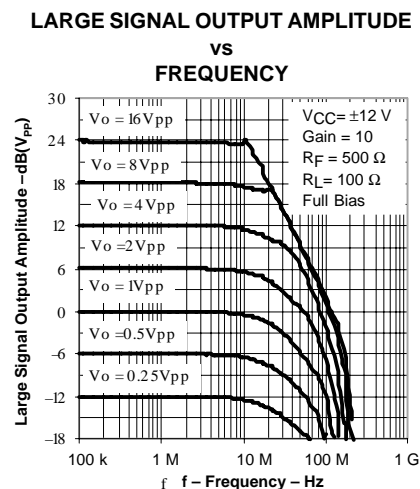


Figure 7

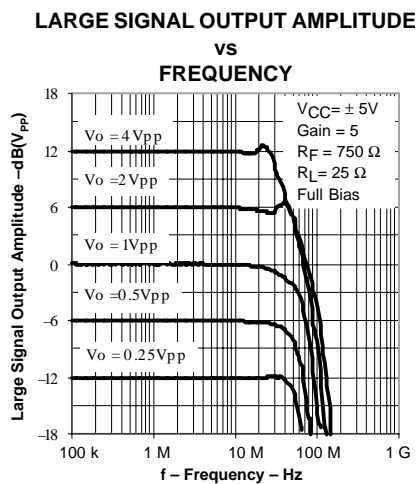


Figure 8

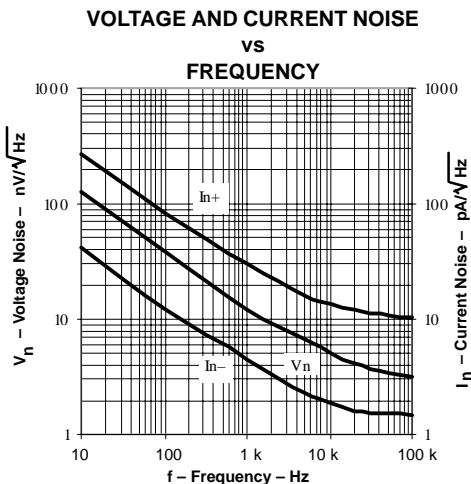


Figure 9

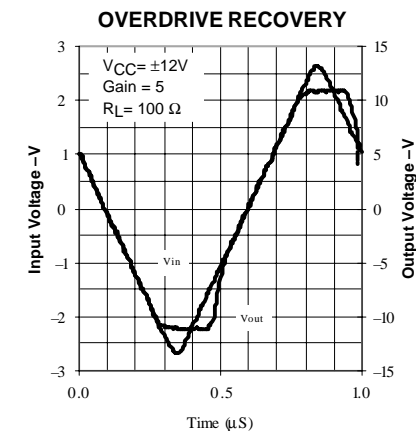


Figure 10

**POWER SUPPLY REJECTION RATIO
VS
FREQUENCY**

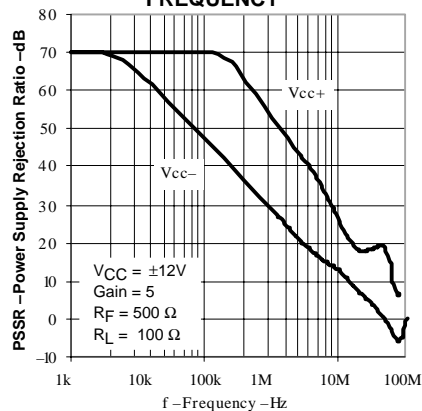


Figure 11

**OUTPUT AMPLITUDE
VS
FREQUENCY**

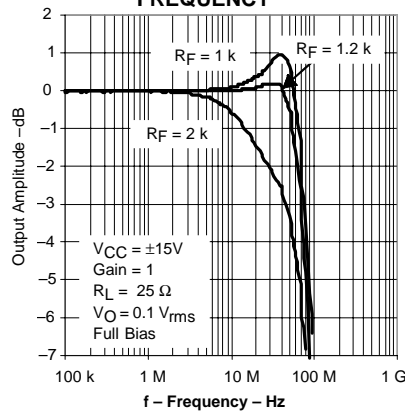


Figure 12

**OUTPUT AMPLITUDE
VS
FREQUENCY**

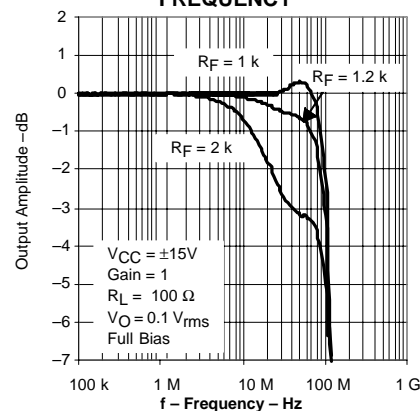


Figure 13

**OUTPUT AMPLITUDE
VS
FREQUENCY**

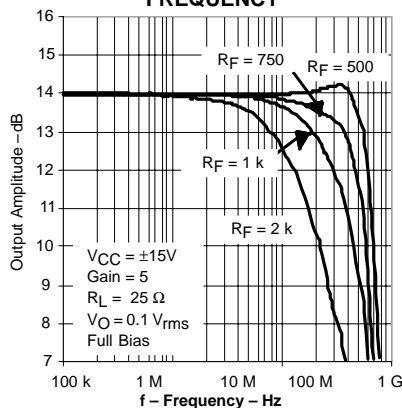


Figure 14

**OUTPUT AMPLITUDE
VS
FREQUENCY**

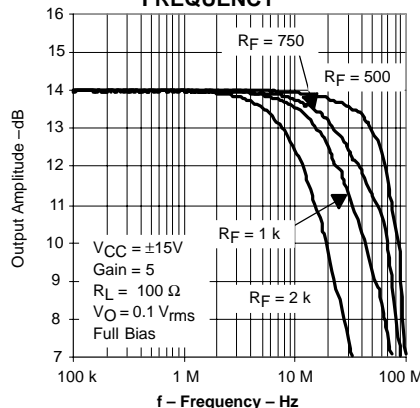


Figure 15

**OUTPUT AMPLITUDE
VS
FREQUENCY**

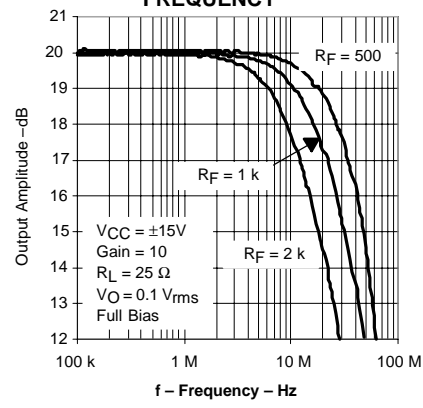


Figure 16

**OUTPUT AMPLITUDE
VS
FREQUENCY**

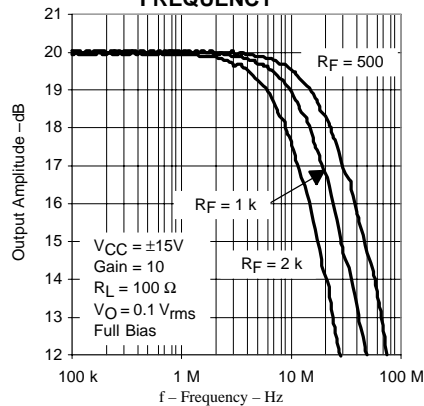


Figure 17

**OUTPUT AMPLITUDE
VS
FREQUENCY**

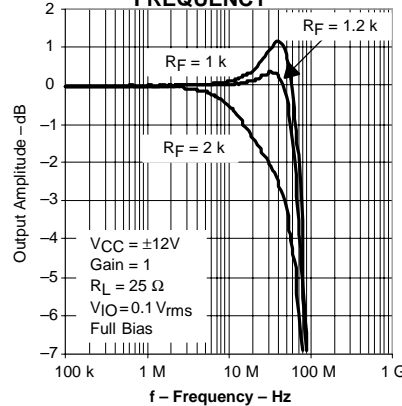


Figure 18

**OUTPUT AMPLITUDE
VS
FREQUENCY**

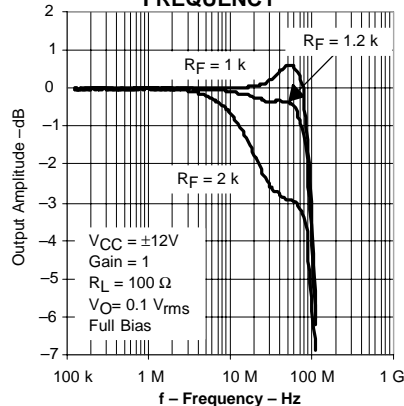


Figure 19

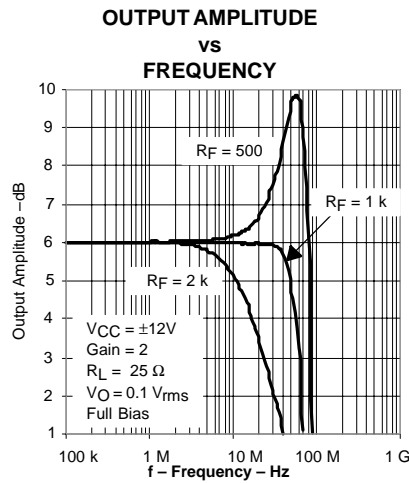


Figure 20

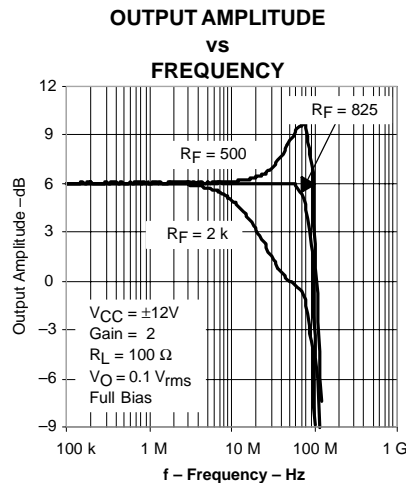


Figure 21

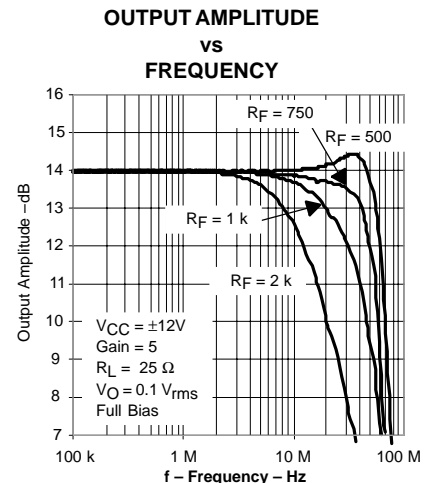


Figure 22

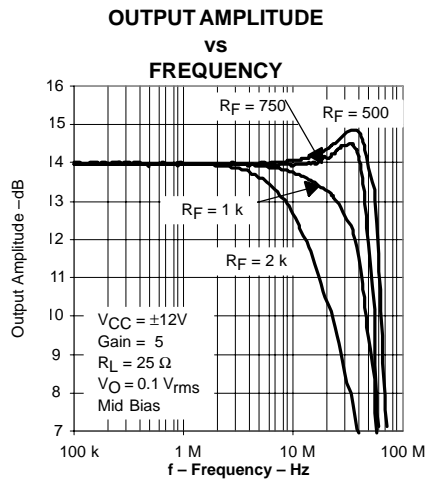


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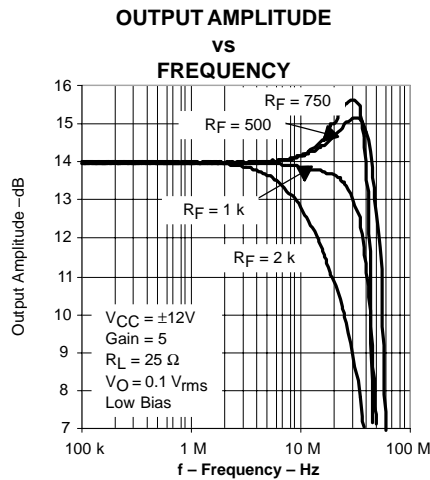


Figure 24

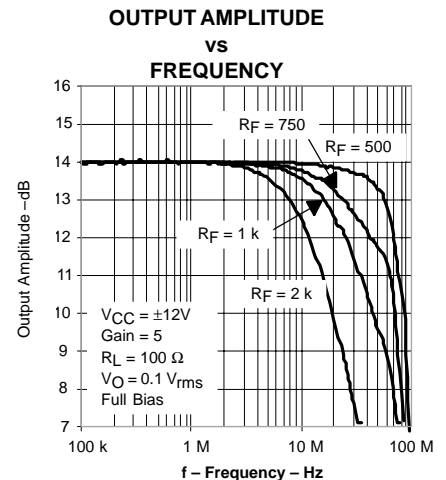


Figure 25

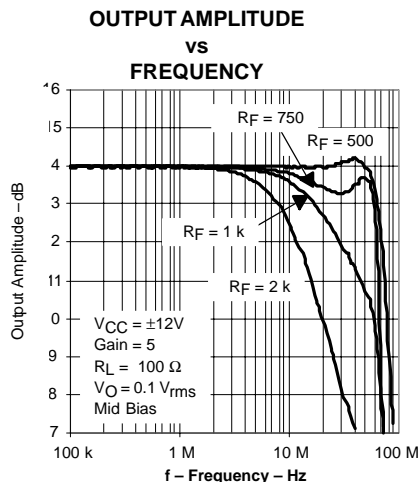


Figure 26

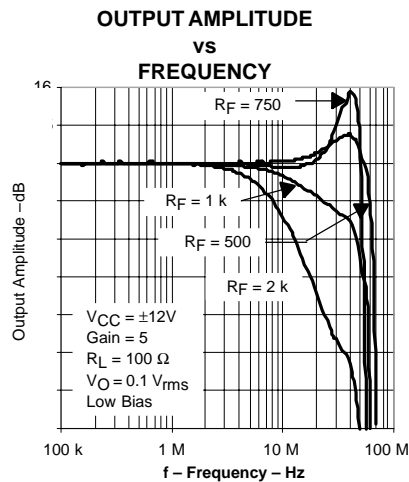


Figure 27

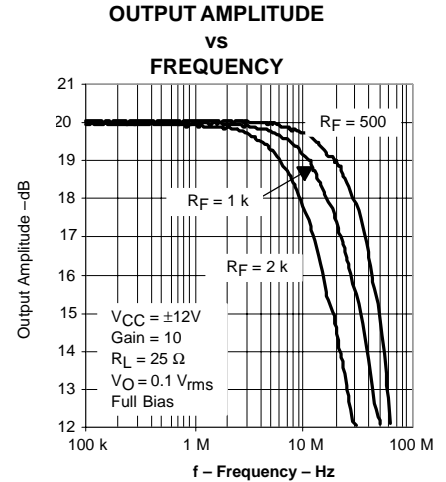


Figure 28

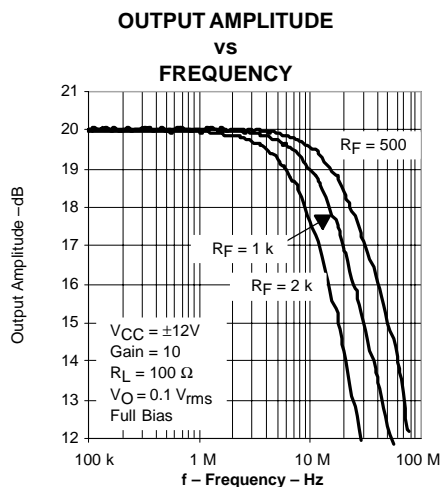


Figure 29

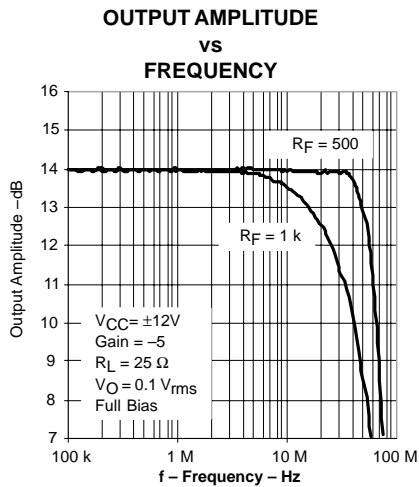


Figure 30

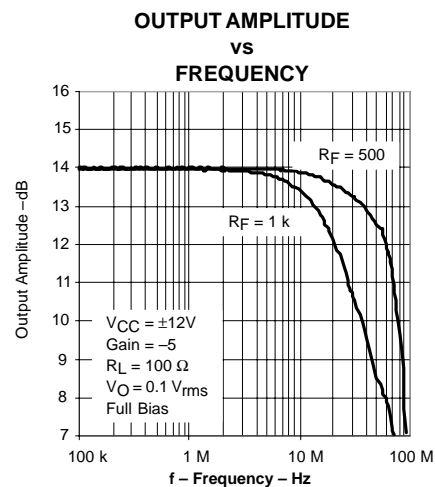


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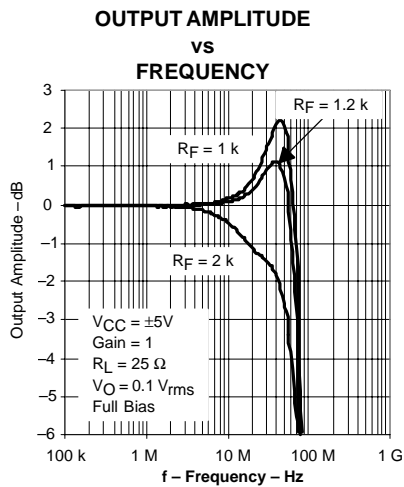


Figure 32

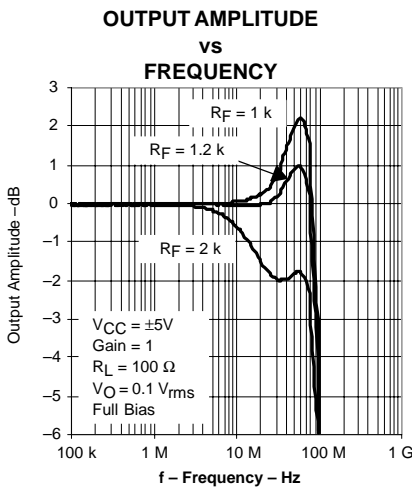


Figure 33

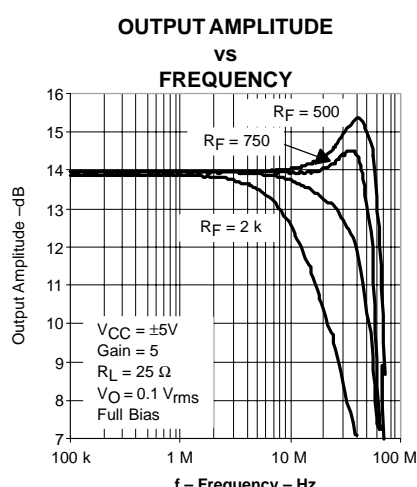


Figure 34

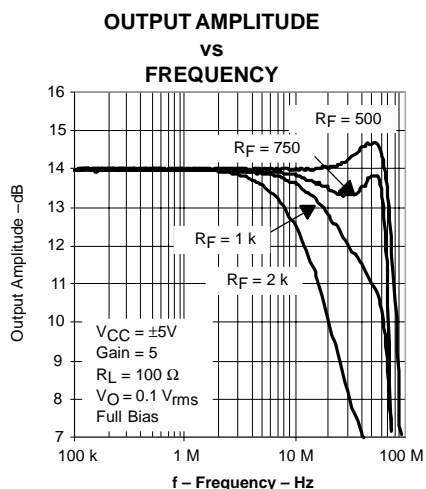


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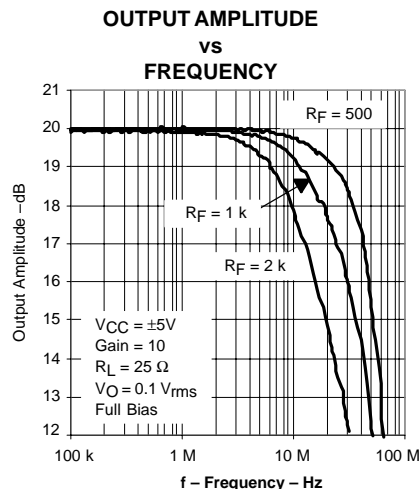


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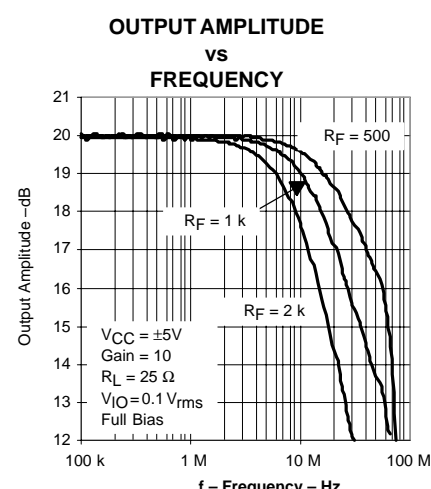
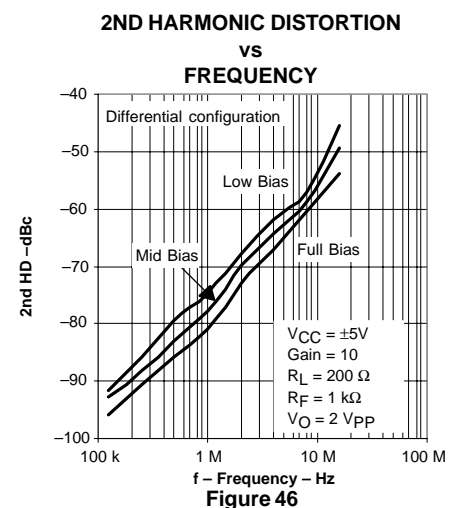
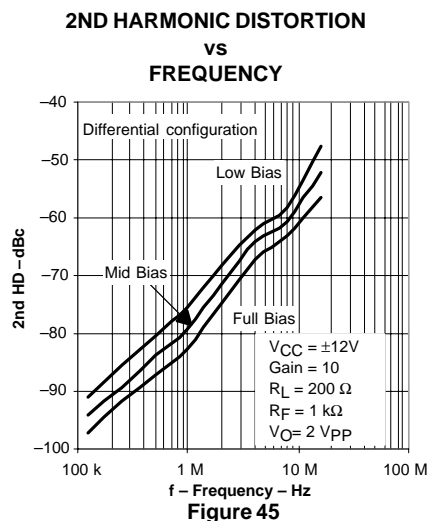
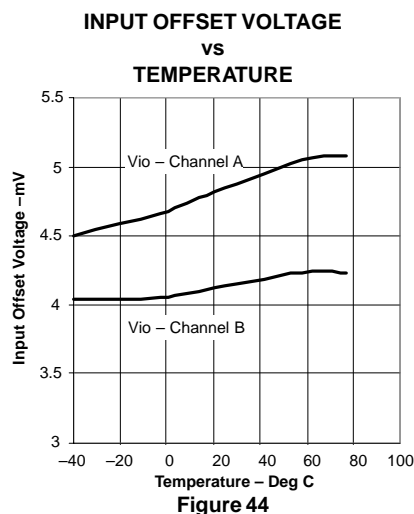
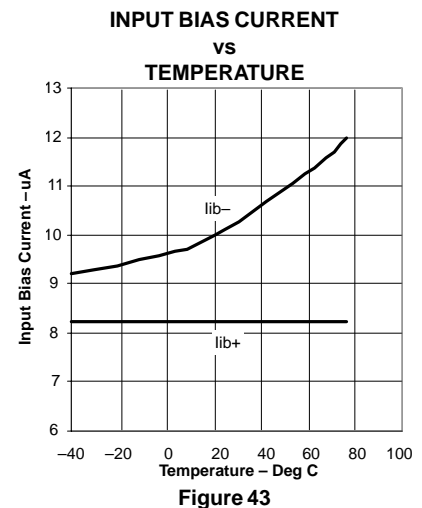
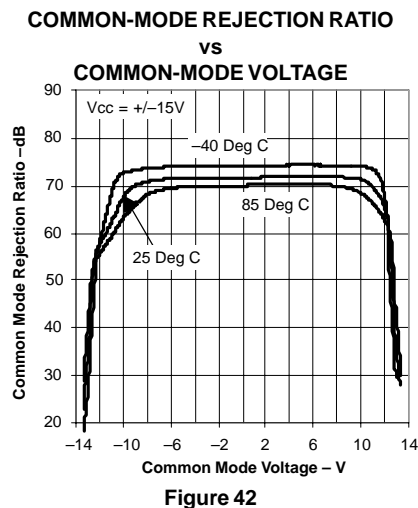
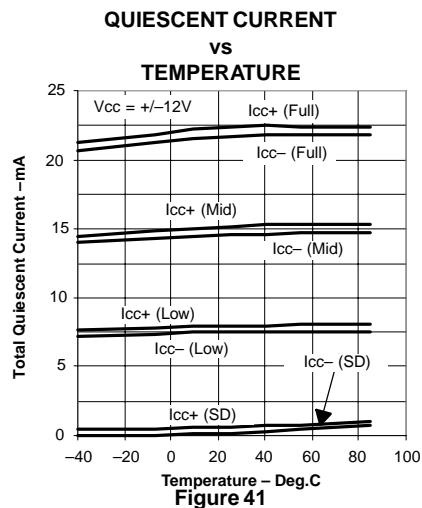
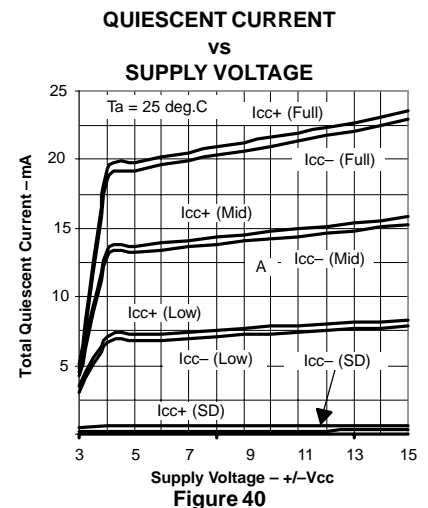
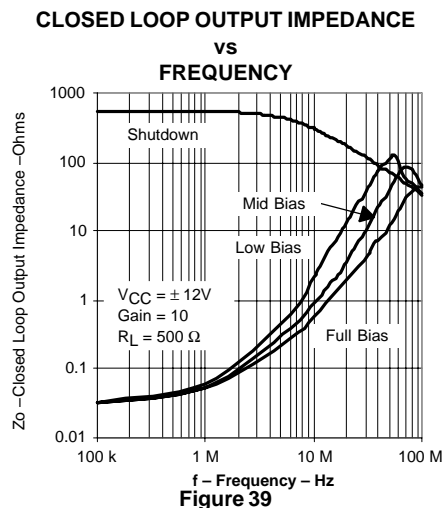
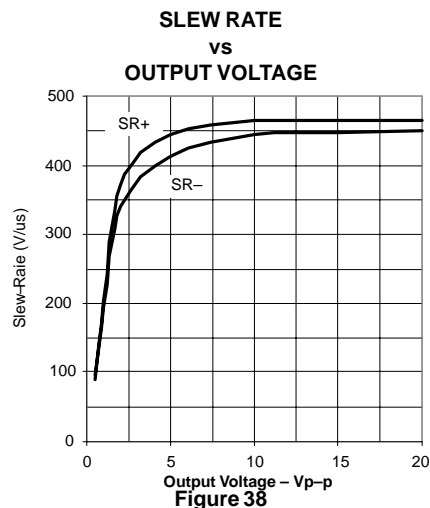


Figure 37



2ND HARMONIC DISTORTION

VS
FREQUENCY

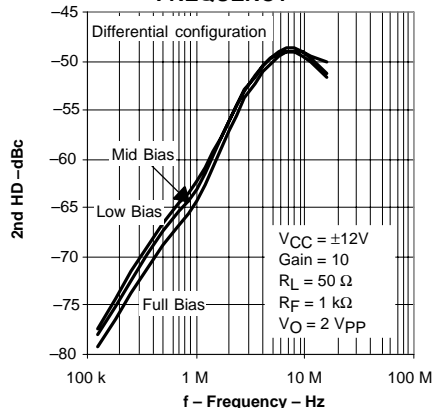


Figure 47

2ND HARMONIC DISTORTION

VS
FREQUENCY

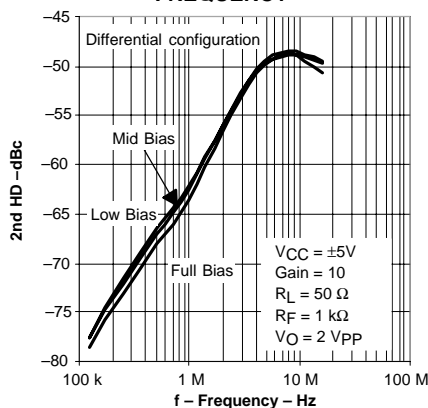


Figure 48

2ND HARMONIC DISTORTION

VS
FREQUENCY

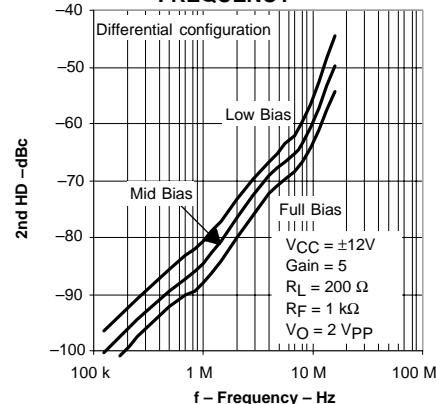


Figure 49

2ND HARMONIC DISTORTION

VS
FREQUENCY

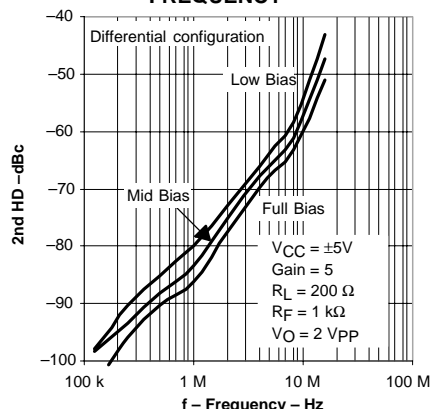


Figure 50

2ND HARMONIC DISTORTION

VS
FREQUENCY

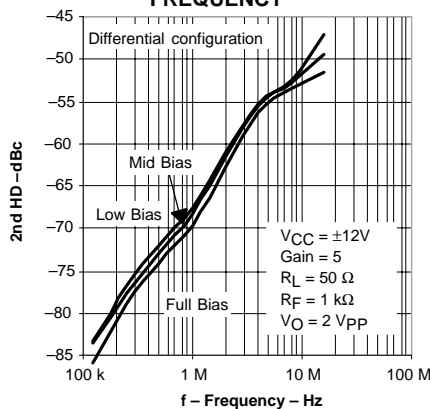


Figure 51

2ND HARMONIC DISTORTION

VS
FREQUENCY

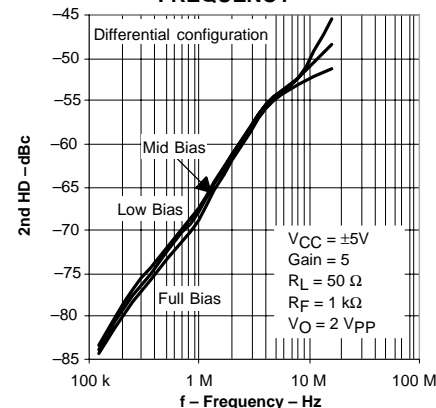


Figure 52

3RD HARMONIC DISTORTION

VS
FREQUENCY

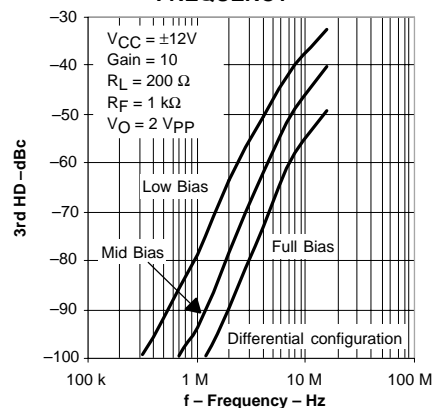


Figure 53

3RD HARMONIC DISTORTION

VS
FREQUENCY

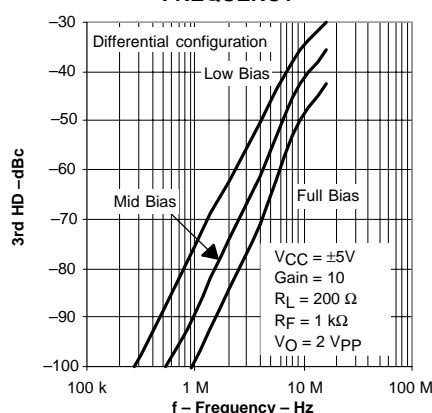


Figure 54

3RD HARMONIC DISTORTION

VS
FREQUENCY

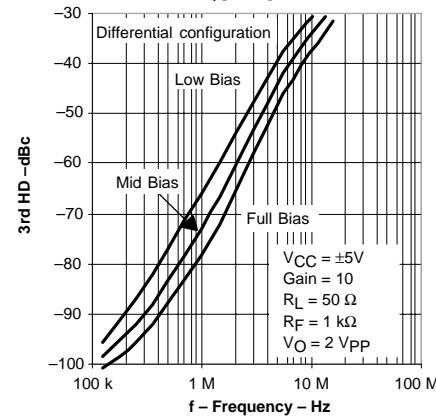


Figure 55

**3RD HARMONIC DISTORTION
vs
FREQUENCY**

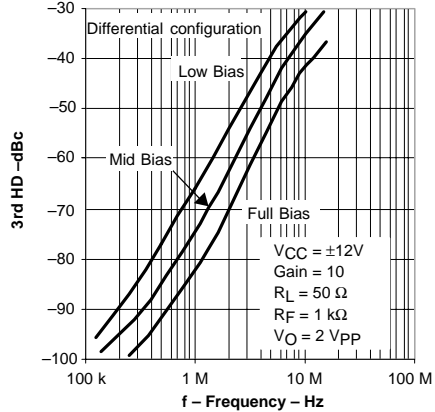


Figure 56

**3RD HARMONIC DISTORTION
vs
FREQUENCY**

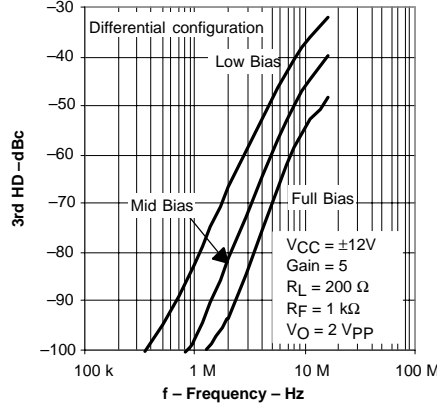


Figure 57

**3RD HARMONIC DISTORTION
vs
FREQUENCY**

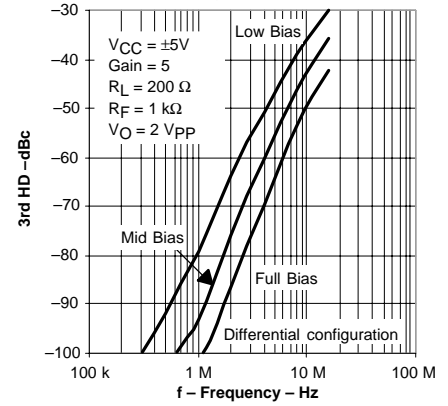


Figure 58

**3RD HARMONIC DISTORTION
vs
FREQUENCY**

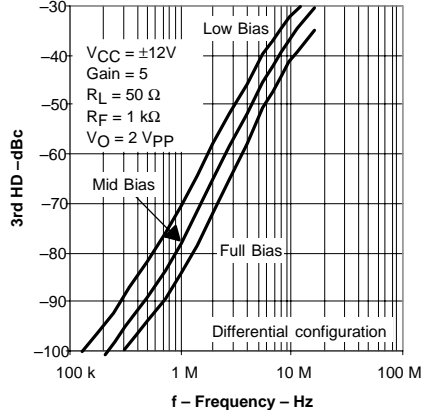


Figure 59

**3RD HARMONIC DISTORTION
vs
FREQUENCY**

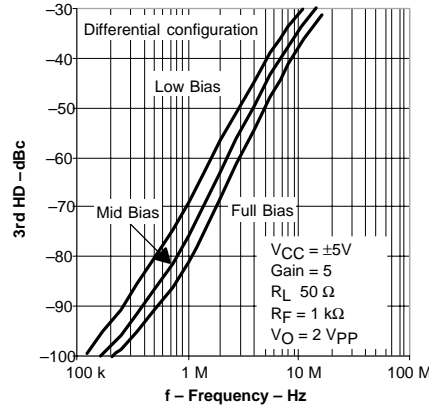


Figure 60

**2ND HARMONIC DISTORTION
vs
OUTPUT VOLTAGE**

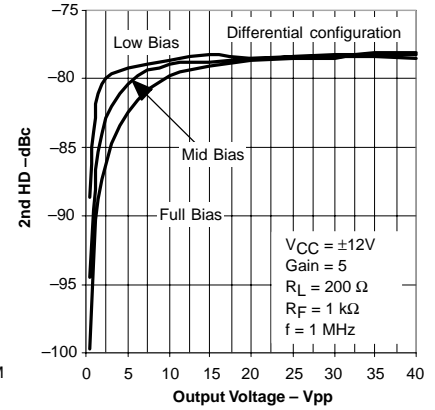


Figure 61

**2ND HARMONIC DISTORTION
vs
OUTPUT VOLTAGE**

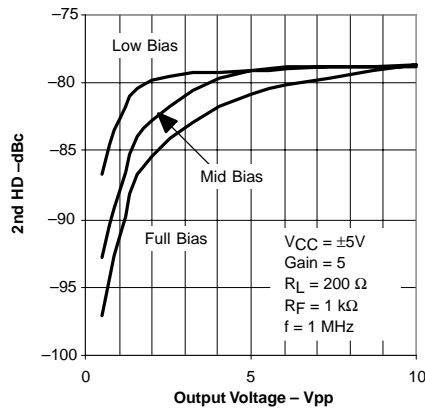


Figure 62

**2ND HARMONIC DISTORTION
vs
OUTPUT VOLTAGE**

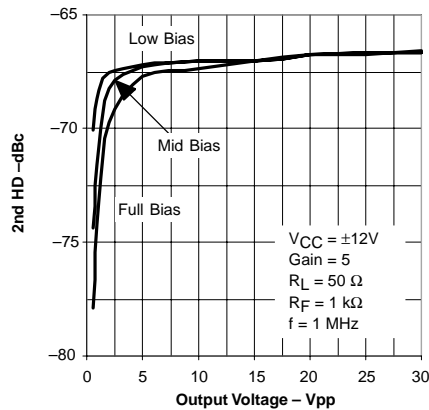


Figure 63

**2ND HARMONIC DISTORTION
vs
OUTPUT VOLTAGE**

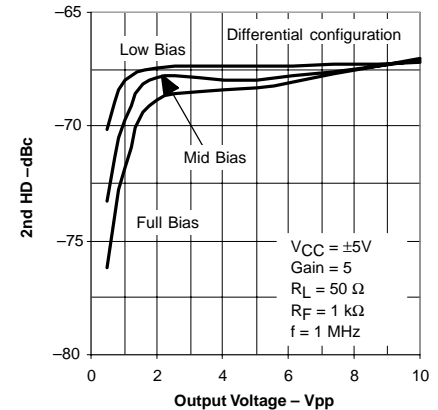
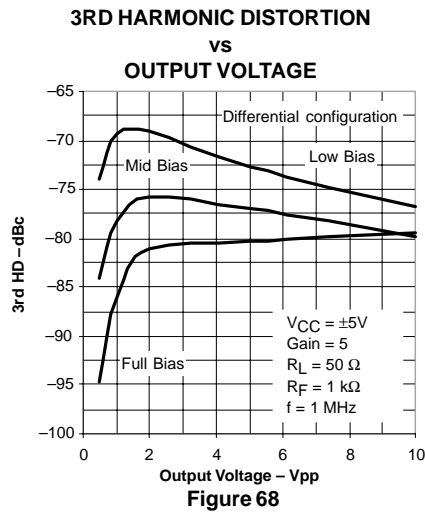
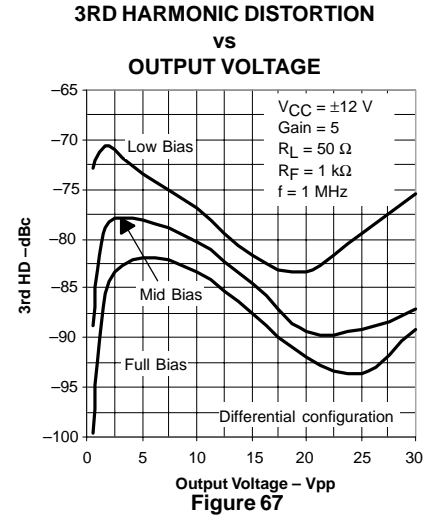
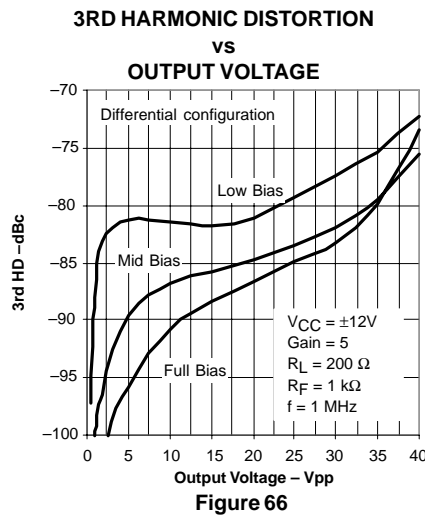
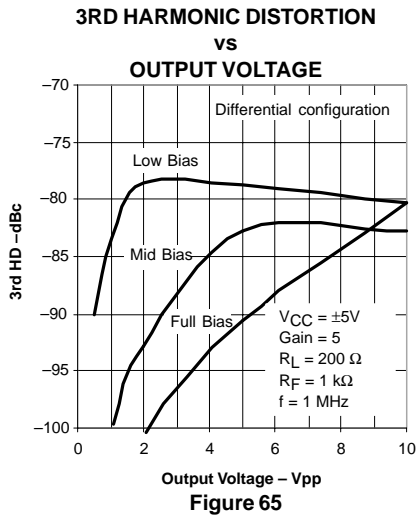


Figure 64



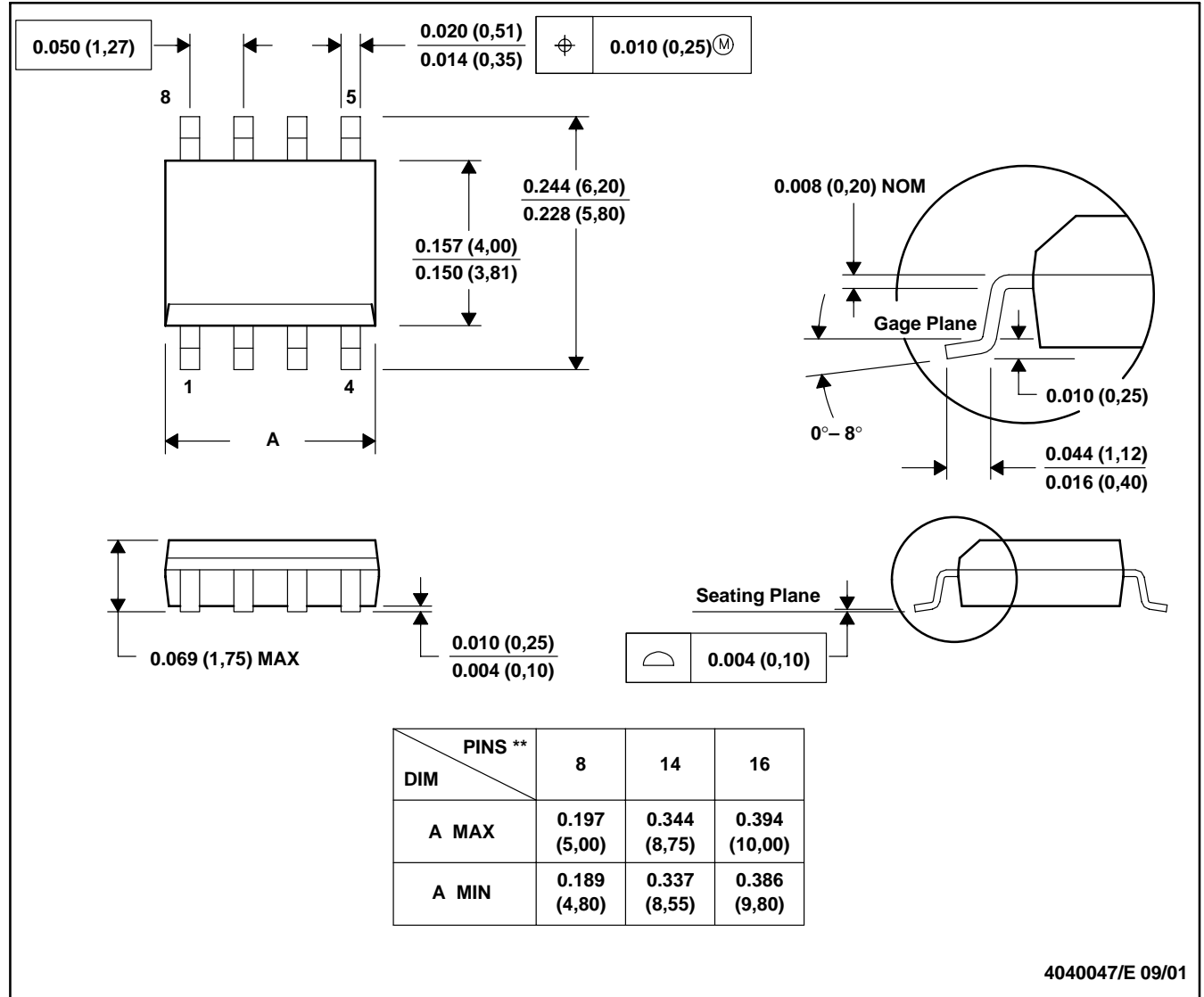
MECHANICAL DATA

MSOI002B – JANUARY 1995 – REVISED SEPTEMBER 2001

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-012

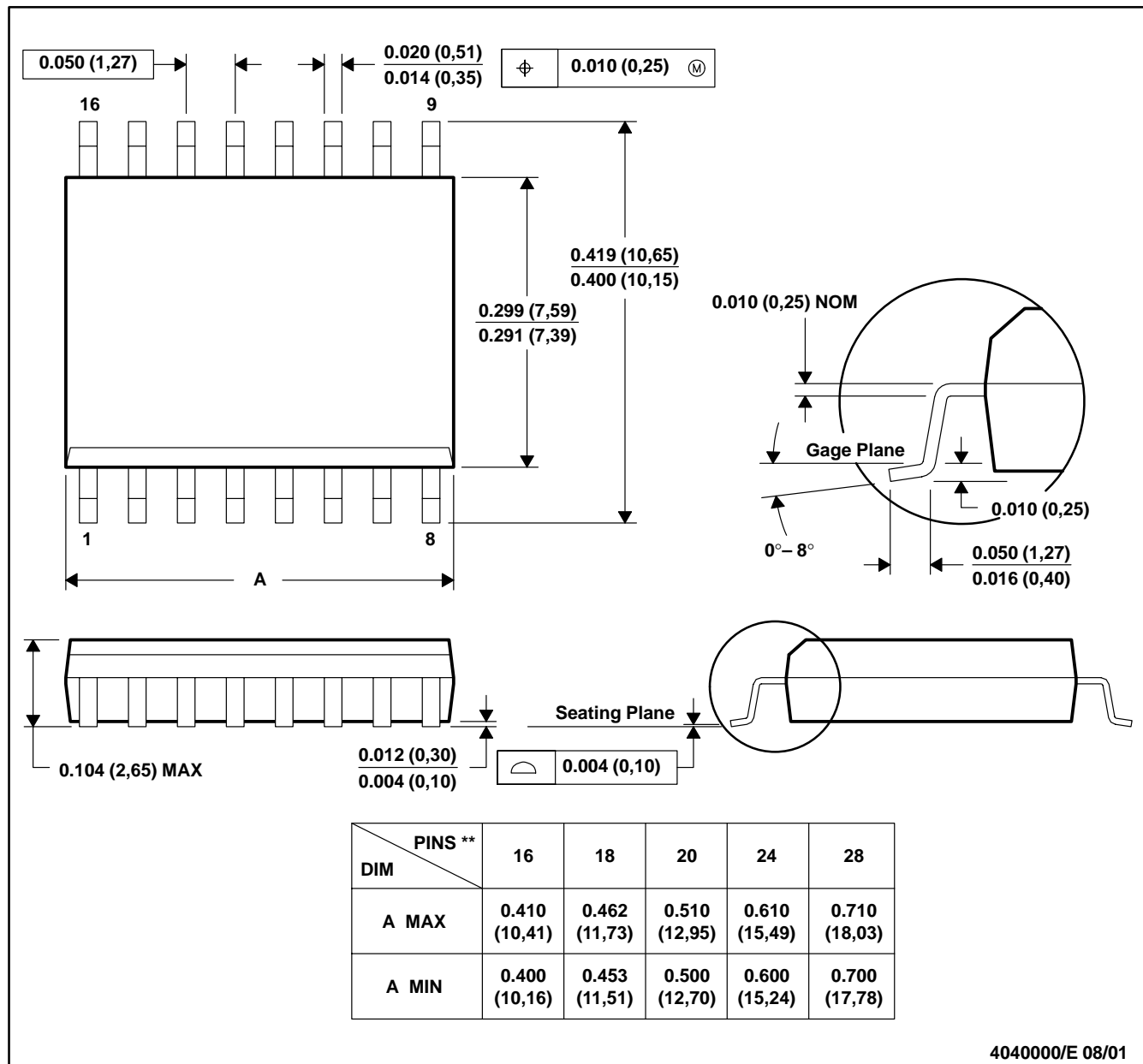
MECHANICAL DATA

MSOI003E – JANUARY 1995 – REVISED SEPTEMBER 2001

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-013

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